SCLS157

- Package Options Include Plastic ''Small Outline'' Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent 4-input positive NOR gates. They perform the Boolean functions:

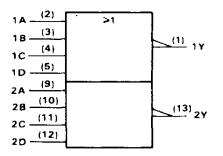
 $Y = \overline{A} + \overline{B} + \overline{C} + \overline{D} \text{ or } Y = \overline{A} \cdot \overline{B} \cdot \overline{C} \cdot \overline{D}$ in positive logic.

The SN54HC4002 is characterized for operation over the full military temperature range of $-55\,^{\circ}$ C to $125\,^{\circ}$ C. The SN74HC4002 is characterized for operation from $-40\,^{\circ}$ C to $85\,^{\circ}$ C.

FUNCTION TABLE

	INP	OUTPUT		
A	B	С	D	Y
н	Х	Х	Х	L
х	н	х	х	L
х	Х	н	х	ί ι
х	х	х	н	L
L	L	L	L	н

logic symbol[†]



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

D2684, DECEMBER 1982-REVISED SEPTEMBER 1987

SN54HC4002 J PACKAGE SN74HC4002 D OR N PACKAGE									
(TO	P VIEW)								
110									
1Y [] 1 1A [] 2 1B [] 3 1C [] 4	14 VCC 13 2Y 12 2D 11 2C								
10115	101128								

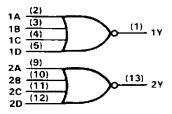
υЦъ	10日 28
NC 🗍 6	9 🗋 2A
GND 🛛 7	8 🗍 NC
-	

SN54HC4002 . . . FK PACKAGE (TOP VIEW)

		14	7	2 Z	VCC VCC	2Υ		_
ļ		3	2	Ϋ	20	19		
1B	b₄						18[2D
NC							17 [NC
1C	<u>]</u> 6						16	2C
NC	þ٦						15[NC
1D	B۱						14[2B
		Å		11	¹²	13		
		ů N	GND	NC	NC	2A		•

NC-No internal connection

logic diagram (positive logic)



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SN54HC4002, SN74HC4002 DUAL 4-INPUT POSITIVE-NOR GATES

absolute maximum ratings over operating free-air temperature range[†]

Supply voltage range, VCC
Input clamp current, I _K (VI < 0 or VI > VCC) $\dots \dots \dots$
Output clamp current, I_{OK} (VO < 0 or VO > VCC) ±20 mA
Continuous output current, IO (VO = 0 to VCC) ±25 mA
Continuous current through VCC or GND pins ±50 mA
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or J package
Lead temperature 1,6 mm (1/16 in) from case for 10 s: D or N package
Storage temperature range

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

			SN	SN54HC4002		SN74HC4002			
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
⊻ін	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15		i	V
		$V_{CC} = 6 V$	4.2			4.2			
		V _{CC} = 2 V	0		0.3	0		0.3	
VIL	Low-level input voltage	$V_{CC} = 4.5 V$	0		0.9	0		0.9	V
		$V_{CC} = 6 V$	0		1.2	0		1.2	
VI	Input voltage		0		Vcc	0		Vcc	V
Vo	Output voltage		0		Vcc_	0		Vcc	V
		V _{CC} = 2 V	0		1000	0		1000	
tt	Input transition (rise and fall) times	$V_{CC} = 4.5 V$	0		500	0		500	ns
-		$V_{CC} = 6 V$	0		400	0		400	
ΤA	Operating free-air temperature		- 55		125	- 40		85	°C

recommended operating conditions

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			T _A = 25°C			SN54HC4002		SN74HC4002		UNIT
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
		2 V	1.9	1.998		1.9		1.9		
	$V_{I} = V_{IH}$ or V_{IL} , $I_{OH} = -20 \ \mu A$	4.5 V	4.4	4.499		4.4		4.4		
∨он		6 V	5.9	5.999		5.9	_	5.9		v
	$V_{I} = V_{IH} \text{ or } V_{IL}, I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.30		3.7		3.84		
	$V_{ } = V_{ }$ or $V_{ }$, $I_{O } = -5.2 \text{ mA}$	6 V	5.48	5.80		5.2		5.34		
	$V_1 = V_{ H}$ or $V_{ L}$, $I_{OL} = 20 \ \mu A$	2 V		0.002	0.1		0.1		0.1	
		4.5 V		0.001	0.1		0.1		0.1	
VoL		6 V		0.001	0.1		0.1		0.1	v
	$V_{\parallel} = V_{\parallel}$ or V_{\parallel} , $I_{0\perp} = 4 \text{ mA}$	4.5 V		0.17	0.26	· · · ·	0.4		0.33	
ľ	$V_{I} = V_{IH}$ or V_{IL} , $I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
	$V_{\rm I} = V_{\rm CC} \text{ or } 0$	6 V		±0.1	±100		±1000	1	1000	nA
^I CC	$V_{I} = V_{CC} \text{ or } 0, I_{O} = 0$	6 V			2		40		20	μA
Ci		2 to 6 V		3	10	1	10		10	рF



SN54HC4002, SN74HC4002 DUAL 4-INPUT POSITIVE-NOR GATES

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted), $C_L = 50 \text{ pF}$ (see Note 1)

	FROM	то		T _A = 25°C			SN54HC4002		SN74HC4002		UNIT
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNU
	•		2 V		44	110	[165		140	
t _{pd}	A thru D	Y	4.5 V		12	22		33		28	ns
			6 V		11	19		28		24	
			2 V		38	75		110		95	
tt		Y	4.5 V		8	15		22		19	กร
-			6 V		6	13		19		16	
· ·				·					L		
Cpd	Power dis	Power dissipation capacitance per gate		No load, T _A = 25°C				25 pF typ			

Note 1: Load circuits and voltage waveforms are shown in Section 1.





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
84044012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
8404401CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
JM38510/65104BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/65104BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54HC4002J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74HC4002N	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	
SNJ54HC4002FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54HC4002J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM



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25-Jan-2012

OTHER QUALIFIED VERSIONS OF SN54HC4002, SN74HC4002 :

Catalog: SN74HC4002

Military: SN54HC4002

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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